

ABSTRACT

PROCESSING METHOD FOR SECTOR-SHAPED WAFER PIECE

Disclosed herein is a processing method for a sector-shaped wafer piece including processing with a processing feed quantity according to the shape of a quarter wafer piece obtained by dividing a wafer into quarters. The processing method includes an information collecting step of collecting information on the shapes of four patterns of the quarter wafer pieces different in the position of a circular arc of an outer periphery and on processing feed quantities corresponding to the shapes of the four patterns, a pattern selection step of holding the quarter wafer piece by a holding surface of a chuck table, calculating a region of a square having vertical and horizontal sides equal to the two sides of the quarter wafer piece, imaging each of the sides by an imaging unit to search for the presence/absence of a target pattern, and selecting that one of the four patterns to which the held quarter wafer piece corresponds, based on the presence/absence of the target patterns, and a processing step of processing the held quarter wafer piece along the division line with a processing feed quantity corresponding to the selected pattern.

(Figure 4)